

### IN THE CLAIMS

Please amend the claims as follows:

1. (Previously Presented) A method of packaging comprising:  
applying an adhesive to a first side of a finished wafer, the first side of the finished wafer having at least one die, the adhesive being one or more of an elastomer applied in fluid form, a thermoplastic material, or a pressure-sensitive film; and  
forming an array of conductive elements within the adhesive to a level to allow the adhesive to contact a support to attach the at least one die to the support, the array of conductive elements electrically coupled to an array of connection pads on the at least one die.
2. (Original) The method of claim 1, wherein forming an array of conductive elements includes:  
creating openings in the adhesive, the openings aligned with the array of connection pads;  
and  
substantially filling the openings with an electrically conductive material.
3. (Original) The method of claim 1, wherein the method is performed in the order presented.
4. (Previously Presented) A method of packaging comprising:  
applying an adhesive to a first side of a finished wafer, the first side of the finished wafer having at least one die, the adhesive being an elastomer applied in fluid form;  
processing the adhesive to create an array of openings therein, the array of openings providing access to an array of connection pads on the at least one die; and  
substantially filling the array of openings with an electrically conductive material to a level to allow the adhesive to contact a support to attach the at least one die to the support.
5. (Original) The method of claim 4, wherein the method further includes applying a protective coating to a second side of the wafer.

6. (Original) The method of claim 4, wherein the method further includes singulating the at least one die from the wafer wherein the at least one die with the adhesive and electrically conductive material form an individual flip chip package.

7. (Original) The method of claim 6, wherein the method further includes surface mounting the flip chip package to a receiving support.

8. (Original) The method of claim 4, wherein the method further includes curing the adhesive.

9. (Original) The method of claim 4, wherein the method is performed in the order presented.

10-26. (Cancelled)

27. (Previously Presented) A method of packaging comprising:  
forming an array of conductive elements within an adhesive layer; and  
applying the adhesive layer to a first side of a finished wafer, the first side of the finished wafer having one or more dice, after forming the array of conductive elements to couple the array of conductive elements electrically to an array of connection pads on a first die of the one or more dice.

28. (Original) The method of claim 27, wherein forming an array of conductive elements within an adhesive layer includes forming openings in the adhesive layer.

29. (Original) The method of claim 28, wherein forming openings in the adhesive layer includes forming openings by laser cutting, chemical etching, or die cutting.

30. (Original) The method of claim 27, wherein forming an array of conductive elements includes forming an array of solder columns.

31. (Original) The method of claim 27, wherein forming an array of conductive elements includes forming an array of solder balls.
32. (Original) The method of claim 27, wherein applying the adhesive layer includes applying the adhesive layer configured as a film.
33. (Original) The method of claim 27, wherein the method further includes singulating the first die from the finished wafer and forming an individual flip chip package.
- 34-58. (Cancelled)
59. (Previously Presented) A method of packaging comprising:  
applying an adhesive to a first side of a finished wafer, the first side of the finished wafer having at least one die, the adhesive being an elastomer applied in fluid form;  
processing the adhesive to create an array of openings therein, the array of openings providing access to an array of connection pads on the at least one die; and  
substantially filling the array of openings with an electrically conductive paste material to a level to allow the adhesive to contact a support to attach the at least one die to the support.
60. (Previously Presented) The method of claim 59, wherein the method includes applying a dispensing apparatus to place the paste in the openings.
61. (Previously Presented) The method of claim 59, wherein the method includes applying stencil/screen techniques to place the paste in the openings.
62. (Previously Presented) The method of claim 59, wherein the adhesive is cured prior to filling the array of openings with an electrically conductive paste material.
63. (Previously Presented) The method of claim 59, wherein the method includes singulating the finished wafer to provide the at least one die as an individual die.

64. (Previously Presented) The method of claim 63, wherein the method includes coupling the at least one die as an individual die to a motherboard.

65. (New) The method of claim 4, wherein applying an adhesive includes applying the adhesive with a chamfer around each of the array of openings.

66. (New) The method of claim 59, wherein applying an adhesive includes applying the adhesive with a chamfer around each of the array of openings.